

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT6752076

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SHENG-YUAN LEE	05/11/2021
RECEIVING PARTY DATA	
Name:	VIA LABS, INC.
Street Address:	7F, 529-1, ZHONGZHENG RD., XINDIAN DIST.
City:	NEW TAIPEI CITY
State/Country:	TAIWAN
Postal Code:	231
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17342684
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	252218-1040
NAME OF SUBMITTER:	DANIEL R. MCCLURE
SIGNATURE:	/Daniel R. McClure/
DATE SIGNED:	06/09/2021
Total Attachments: 1	
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ASSIGNMENT

WHEREAS, Sheng-Yuan Lee
hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as
described and set forth in the below identified application for United States Letters Patent:

Title: MULTILAYER-TYPE ON-CHIP INDUCTOR STRUCTURE

Filed: _____ Serial No. _____
Executed on: _____

WHEREAS, VIA LABS, INC. of 7F, 529-1, Zhongzheng Rd., Xindian Dist., New Taipei City 231, Taiwan hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S
interest in the said invention and application and in any U.S. Letters Patent which may be granted
on the same;

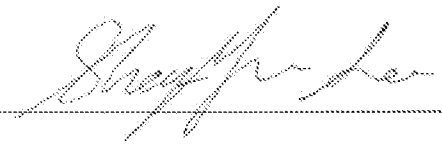
NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and
valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have
sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said
Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to
the said invention and application and all future improvements thereon, and in and to any Letters
Patent which may hereafter be granted on the same in the United States, and the entire rights, title
and interest in and to any and all foreign patents and applications for any invention described in said
U.S. patent applications, in any and all countries foreign to the U.S., including all rights of priority
arising from them, and all the rights and privileges under any and all forms of protection, including
patents, that may be granted in said countries foreign to the U.S. for them, the said interest to be held
and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by
said Assignor had this Assignment and transfer not been made, to the full end and term of any
Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or
in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee,
but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or
applications, execute, verify, acknowledge and deliver all such further papers, including
applications for Letters Patent and for the reissue thereof, and instruments of assignment and
transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or
maintain Letters Patent for said invention and improvement, and to vest title thereto in said
Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s)
indicated.

May 11, 2021

Date


Name: Sheng-Yuan Lee